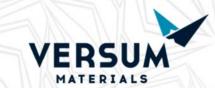
Dynasolve 217

Cured Silicone Cleaning Solvent





Dynasolve 217 is a reactive formulated solvent which is used to remove cured silicones in both electronic and industrial applications.

CLEANING APPLICATIONS:

Depotting and decapsulating of electronic components

Conformal coating removal

Industrial silicone removal and cleaning

ADVANTAGES:

More efficient than acetone, MEK and other solvents

Formulated to be highly selective

Non-chlorinated

Ability to use at room temperature

High resin loading capacity allows for reuse and reduced cost of ownership

SPECIFICATIONS:

Specific gravity:	0.84
Boiling point:	>365°F (185°C)
Flash point:	201°F (94°C)

MATERIALS REMOVED:

Cured silicone

PRODUCT USAGE GUIDELINES

(SEE SDS FOR EH&S INFORMATION)

1. Ensure the part is completely free of water.

Do not immerse in aluminum for more than 8 hours

- 2. Immerse part in Dynasolve 217 at 150°F (65°C).
- Once cured silicone has been removed, it is critical to rinse with alcohol prior to rinsing with water.

MATERIAL COMPATIBILITY:

Recommended materials including:	
All metals	
Teflon®	
Polyethylene and polypropylene	
Avoid materials including:	
Nylon	
PVC	



For more information, please contact us at:

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